

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: Islam et al. Date: July 24, 2009  
Application No.: 10/561,381 Examiner: F.F.Y. Lopez  
Filing Date: December 16, 2005 Group Art Unit: 2826  
Title: LEAD FRAME ROUTED CHIP PADS FOR SEMICONDUCTOR PACKAGES

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. § 1.116**

Sir:

In response to the final Office Action mailed May 27, 2009, the Examiner is respectfully requested to amend the above-identified application as follows.

Amendments to the claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.

**CERTIFICATE OF MAILING OR TRANSMISSION (37 C.F.R. § 1.8(a))**

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

- deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
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July 24, 2009

Signed: Brenda Musco  
Brenda Musco